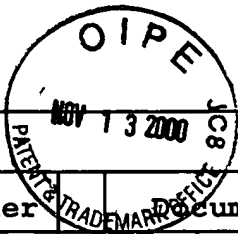


INFORMATION DISCLOSURE CITATION

Docket: 550718-077	Ser. No. 09/691,017
Applicant: Haruo Kamei	
Filed: 10/18/00	Group:



U.S. PATENT DOCUMENTS

Examiner	Document No.	Date	Name	Class	Sub	
WB	5 4 2 3 7 1 3	6/95	Mishima	451	36	

FOREIGN PATENT DOCUMENTS

Trans

Examiner	Document No.	Date	Country	Class	Sub	Y	N

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

WB		U.S. Patent Application No. 08/826,344 entitled Method and Apparatus for Grinding the Surface of a Work

Examiner: W. H. C. Berry, Jr.	Date Considered: 7/1/01
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* Examiner: Initial if reference considered, whether or not citation is conformance with MPEP 609. Draw line through citation is not in conformance and not considered. Include copy of this form with next communication to applicant.